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National Standards Authority of Ireland

IRISH STANDARD

I.S. EN 61189-5:2006

ICS 31.180

TEST METHODS FOR ELECTRICAL MATERIALS, INTERCONNECTION STRUCTURES AND ASSEMBLIES -- PART 5: TEST METHODS FOR PRINTED BOARD ASSEMBLIES (IEC 61189-5:2006 (EQV))

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 61189-5

September 2006

ICS 31.180

English version

Test methods for electrical materials, interconnection structures and assemblies
Part 5: Test methods for printed board assemblies
(IEC 61189-5:2006)

Méthodes d'essais pour les matériaux électriques, les structures d'interconnexion et les ensembles
Partie 5: Méthodes d'essais pour les cartes imprimées équipées
(CEI 61189-5:2006)

Prüfverfahren für Elektromaterialien, Verbindungsstrukturen und Baugruppen
Teil 5: Prüfverfahren für bestückte Leiterplatten
(IEC 61189-5:2006)

This European Standard was approved by CENELEC on 2006-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC
European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

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Foreword

The text of document 91/564/FDIS, future edition 1 of IEC 61189-5, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61189-5 on 2006-09-01.

This standard forms part of a series and should be used in conjunction with other parts in the same series, under the main title *Test methods for electrical materials, interconnection structures and assemblies:*

Part 1: General test methods and methodology

Part 2: Test methods for materials for interconnection structures

Part 3: Test methods for interconnection structures (printed boards)

Part 4: Test methods for electronic components assembling characteristics

Part 5: Test methods for printed board assemblies

Part 6: Test methods for materials used in electronic assemblies

It should also be read in conjunction with EN 60068, Environmental testing.

The following dates were fixed:

– latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2007-06-01
– latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2009-09-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 61189-5:2006 was approved by CENELEC as a European Standard without any modification.

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60068-1	1988	Environmental testing Part 1: General and guidance	EN 60068-1[1)]	1994
IEC 60068-2-20	-[2)]	Environmental testing Part 2: Tests - Test T: Soldering	HD 323.2.20 S3	1988[3)]
IEC 61189-1	-[2)]	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 1: General test methods and methodology	EN 61189-1	1997[3)]
IEC 61189-3	-[2)]	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 3: Test methods for interconnection structures (printed boards)	EN 61189-3	1997[3)]
IEC 61189-6	-[2)]	Test methods for electrical materials, interconnection structures and assemblies Part 6: Test methods for materials used in manufacturing electronic assemblies	EN 61189-6	2006[3)]
IEC 61190-1-1	-[2)]	Attachment materials for electronic assembly Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly	EN 61190-1-1	2002[3)]
IEC 61190-1-2	2002	Attachment materials for electronic assembly Part 1-2: Requirements for solder pastes for high-quality interconnections in electronics assembly	EN 61190-1-2	2002
IEC 61190-1-3	-[2)]	Attachment materials for electronic assembly Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	2002[3)]

[1)] EN 60068-1 includes corrigendum October 1988 + A1:1992 to IEC 60068-1.

[2)] Undated reference.

[3)] Valid edition at date of issue.

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Publication	Year	Title	EN/HD	Year
IEC 61249-2-7	-[2)]	Materials for printed boards and other interconnecting structures Part 2-7: Reinforced base materials, clad and unclad - Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad	EN 61249-2-7 + corr. September	2002[3)] 2005
IEC 62137 + corr. January	2004 2005	Environmental and endurance testing - Test methods for surface-mount boards of area array type packages FBGA, BGA, FLGA, LGA, SON and QFN	EN 62137 + corr. February	2004 2005
ISO 5725-2	-[2)]	Accuracy (trueness and precision) of measurement methods and results Part 2: Basic method for the determination of repeatability and reproducibility of a standard measurement method	-	-
ISO 9001	-[2)]	Quality management systems - Requirements	EN ISO 9001	2000[3)]
ISO 9455-1	-[2)]	Soft soldering fluxes - Test methods Part 1: Determination of non-volatile matter, gravimetric method	EN 29455-1	1993[3)]
ISO 9455-2	-[2)]	Soft soldering fluxes - Test methods Part 2: Determination of non-volatile matter, ebulliometric method	EN ISO 9455-2	1995[3)]

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